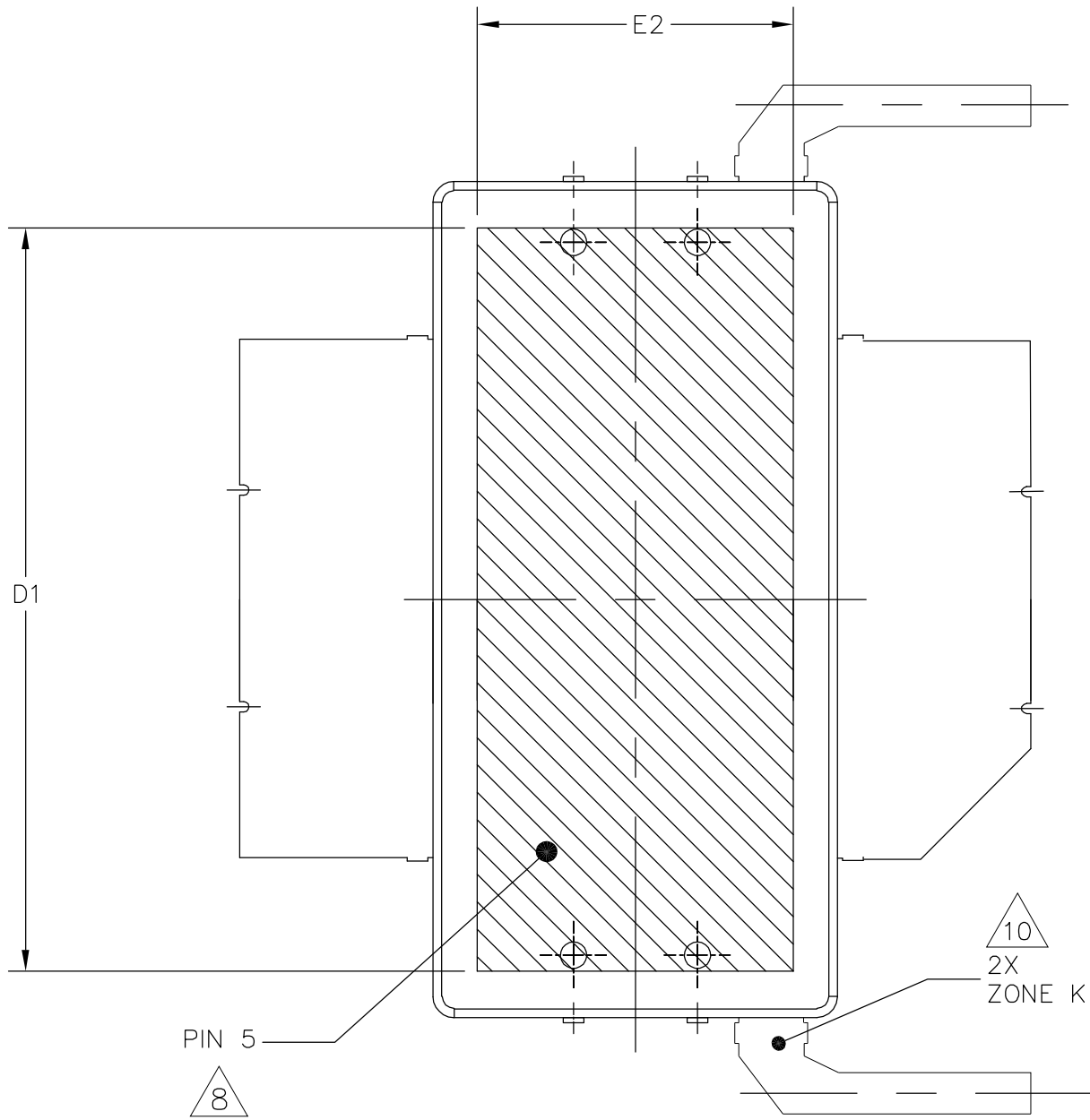


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BOTTOM VIEW
VIEW T-T

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NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE H IS LOCATED AT TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS DD AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 INCH (0.15 MM) PER SIDE. DIMENSIONS DD AND E1 DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
5. DIMENSION bb DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 INCH (0.13 MM) TOTAL IN EXCESS OF THE bb DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. DATUMS A AND B TO BE DETERMINED AT DATUM PLANE H.
7. DIMENSIONS A1 AND A2 APPLIES WITHIN ZONE J ONLY. A1 APPLIES TO PINS 1 AND 3. A2 APPLIES TO PINS 2 AND 4. TOLERANCES OF DIMENSIONS A1 AND A2 ARE TENTATIVE.
8. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG. THE DIMENSIONS D1 AND E2 REPRESENT THE VALUES BETWEEN THE TWO OPPOSITE POINTS ALONG THE EDGES OF EXPOSED AREA OF HEAT SLUG.
9. DIMPLED HOLE REPRESENTS INPUT SIDE.
10. ZONE K REPRESENTS NON-SOLDERABLE REGION WHERE MOLD FLASH AND RESIN BLEED ARE PERMITTED ON BOTH SIDES OF THE LEADS.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
AA	.148	.152	3.76	3.86	W1	.095	.105	2.41	2.67
A1	.059	.065	1.50	1.65	W2	.158	.168	4.01	4.27
A2	.056	.068	1.42	1.73	W3	.138	.148	3.51	3.76
DD	.808	.812	20.52	20.62	U	.037	.043	0.94	1.09
D1	.720	----	18.29	----	Y	.956 BSC		24.28 BSC	
E	.762	.770	19.35	19.56	bb	.497	.503	12.62	12.78
E1	.390	.394	9.91	10.01	c1	.007	.011	0.18	0.28
E2	.306	----	7.77	----	e1	.116	.124	2.95	3.15
E3	.383	.387	9.73	9.83	aaa	.004		0.10	
F	.025 BSC		0.64 BSC		bbb	.006		0.15	
G	.030 BSC		0.76 BSC		ccc	.010		0.25	

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MECHANICAL OUTLINE

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